

WEST Search History

DATE: Wednesday, October 01, 2003

Set Name Query
side by side

Hit Count Set Name
result set

DB=USPT,PGPB,JPAB,EPAB,DWPI; PLUR=YES; OP=ADJ

L1	copper with (plating or electroplating or electroplated or electroplate or electrodeposit or electrodepositing or electrodeposited or electrodeposition)	38726	L1
L2	brightener or carrier	1074582	L2
L3	protein near3 (polymer or polymeric)	10665	L3
L4	L2 or dimethylamino or dimethylaminopropyl or melamine or formaldehyde	1249591	L4
L5	l1 with (acid or acidic)	4201	L5
L6	leveller or leveler or levelling or leveling	67862	L6
L7	16 or (allylamine or polyaniline or hexanediamine or polyacrylamide or formaldehyde or dimethylammonium or diallyldimethylammonium or vinylpyridine or trimethylquinoline)	299701	L7
L8	carrier or polysaccharide or polyethylene glycol or ethylene oxide	1060192	L8
L9	carrier or polysaccharide or starch or cellulose or amylopectin or amylose or polyethylene glycol or ethylene oxide	1474998	L9
L10	15 and 12 and 17 and 19	319	L10
L11	L10 and brightener	209	L11
L12	L11 and 13	1	L12
L13	L11 and 13	1	L13
L14	L11 and (205/\$.ccls. or 252/\$.ccls.)	159	L14
L15	16 with (allylamine or polyaniline or hexanediamine or polyacrylamide or formaldehyde or dimethylammonium or diallyldimethylammonium or vinylpyridine or trimethylquinoline)	142	L15
L16	12 and 15 and 19 and L15	6	L16

END OF SEARCH HISTORY

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Search Results - Record(s) 1 through 6 of 6 returned.☐ 1. Document ID: US 20030172969 A1

L16: Entry 1 of 6

File: PGPB

Sep 18, 2003

PGPUB-DOCUMENT-NUMBER: 20030172969

PGPUB-FILING-TYPE: new

DOCUMENT-IDENTIFIER: US 20030172969 A1

TITLE: Process for depositing metal contacts on a buried grid solar cell and solar cell obtained by the process

PUBLICATION-DATE: September 18, 2003

INVENTOR-INFORMATION:

NAME	CITY	STATE	COUNTRY	RULE-47
Jenson, Jens Dahl	Virum		DK	
Moller, Per	Esrum		DK	
Brunel Mason, Nigel	Camberley, Surrey		GB	
Russel, Richard Walter John	San Augustin de Guad alix		ES	
Verhoeven, Peter	Vaught		NL	

US-CL-CURRENT: 136/252; 438/57

Full	Title	Citation	Front	Review	Classification	Date	Reference	Sequences	Attachments	Claims	KWC	Draw. Desc	Image
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☐ 2. Document ID: US 4384930 A

L16: Entry 2 of 6

File: USPT

May 24, 1983

US-PAT-NO: 4384930

DOCUMENT-IDENTIFIER: US 4384930 A

TITLE: Electroplating baths, additives therefor and methods for the electrodeposition of metals

DATE-ISSUED: May 24, 1983

INVENTOR-INFORMATION:

NAME	CITY	STATE	ZIP CODE	COUNTRY
Eckles; William E.	Cleveland Heights	OH		

US-CL-CURRENT: 205/253; 205/254, 205/281, 205/296, 205/298, 205/299, 205/302, 205/303, 205/304, 205/313, 205/314

Full	Title	Citation	Front	Review	Classification	Date	Reference	Sequences	Attachments	Claims	KWC	Draw. Desc	Image
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☐ 3. Document ID: US 4347108 A

L16: Entry 3 of 6

File: USPT

Aug 31, 1982

US-PAT-NO: 4347108

DOCUMENT-IDENTIFIER: US 4347108 A

TITLE: Electrodeposition of copper, acidic copper electroplating baths and additives therefor

DATE-ISSUED: August 31, 1982

INVENTOR-INFORMATION:

NAME	CITY	STATE	ZIP CODE	COUNTRY
Willis; William J.	North Royalton	OH		

US-CL-CURRENT: 205/298; 252/182.1

Full	Title	Citation	Front	Review	Classification	Date	Reference	Sequences	Attachments	Claims	KMIC	Draw Desc	Image
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☐ 4. Document ID: US 4134803 A

L16: Entry 4 of 6

File: USPT

Jan 16, 1979

US-PAT-NO: 4134803

DOCUMENT-IDENTIFIER: US 4134803 A

TITLE: Nitrogen and sulfur compositions and acid copper plating baths

DATE-ISSUED: January 16, 1979

INVENTOR-INFORMATION:

NAME	CITY	STATE	ZIP CODE	COUNTRY
Eckles; William E.	Cleveland Heights	OH		
Starinshak; Thomas W.	Berea	OH		

US-CL-CURRENT: 205/296

Full	Title	Citation	Front	Review	Classification	Date	Reference	Sequences	Attachments	KMIC	Draw Desc	Image
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☐ 5. Document ID: US 4038161 A

L16: Entry 5 of 6

File: USPT

Jul 26, 1977

US-PAT-NO: 4038161

DOCUMENT-IDENTIFIER: US 4038161 A

TITLE: Acid copper plating and additive composition therefor

DATE-ISSUED: July 26, 1977

INVENTOR-INFORMATION:

NAME	CITY	STATE	ZIP CODE	COUNTRY
Eckles; William Edward	Cleveland Heights	OH		
Starinshak; Thomas Walter	Berea	OH		

US-CL-CURRENT: 205/298; 205/297, 528/405

Full	Title	Citation	Front	Review	Classification	Date	Reference	Sequences	Attachments
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KWIC	Draw Desc	Image
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☐ 6. Document ID: US 3944390 A

L16: Entry 6 of 6

File: USPT

Mar 16, 1976

US-PAT-NO: 3944390

DOCUMENT-IDENTIFIER: US 3944390 A

TITLE: Workpiece surface area determination

DATE-ISSUED: March 16, 1976

INVENTOR-INFORMATION:

NAME	CITY	STATE	ZIP CODE	COUNTRY
Lieber; Hans-Wilhelm	Berlin			DT

US-CL-CURRENT: 436/5; 205/775, 436/174

Full	Title	Citation	Front	Review	Classification	Date	Reference	Sequences	Attachments
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KWIC	Draw Desc	Image
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Terms	Documents
12 and 15 and 19 and L15	6

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DATE: Wednesday, October 01, 2003

<u>Set Name</u>	<u>Query</u>	<u>Hit Count</u>	<u>Set Name</u>
side by side			result set
	<i>DB=USPT,PGPB,JPAB,EPAB,DWPI; PLUR=YES; OP=ADJ</i>		
L1	wang-qing\$.in. or huang-weiji\$.in. or lau-miu\$.in. or liu-carol\$.in. or ma-ce\$.in. or chang-edward\$.in. or ho-wenpin\$.in. or paciej-richard\$.in.	133	L1
L2	L1 and copper	23	L2
L3	L2 and (organic with (leveller or leveler or levelling or leveling))	2	L3

END OF SEARCH HISTORY

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Search Results - Record(s) 1 through 2 of 2 returned.

☐ 1. Document ID: JP 2001073182 A

L3: Entry 1 of 2

File: JPAB

Mar 21, 2001

PUB-NO: JP02001073182A

DOCUMENT-IDENTIFIER: JP 2001073182 A

TITLE: IMPROVED ACIDIC COPPER ELECTROPLATING SOLUTION

PUBN-DATE: March 21, 2001

INVENTOR-INFORMATION:

NAME

COUNTRY

KIN, MIN WAN

HUANG, WEIJI

LAU, MIU LING

LIU, CAROL HSIUCHIN

MA, CE

CHANG, EDWARD K

HO, WENPIN

PACIEJ, RICHARD C

INT-CL (IPC): C25 D 3/38; C25 D 7/12; H01 L 21/288

Full	Title	Citation	Front	Review	Classification	Date	Reference	Sequences	Attachments
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KWIC	Draw Desc	Image
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☐ 2. Document ID: EP 1069211 A2

L3: Entry 2 of 2

File: EPAB

Jan 17, 2001

PUB-NO: EP001069211A2

DOCUMENT-IDENTIFIER: EP 1069211 A2

TITLE: Electroplating solutions

PUBN-DATE: January 17, 2001

INVENTOR-INFORMATION:

NAME

COUNTRY

WANG, QING MIN

US

HUANG, WEIJI

US

LAU, MIU LING

US

LIU, CAROL HSIUCHIN

US

MA, CE

US

CHANG, EDWARD K

US

HO, WENPIN

US

PACIEJ, RICHARD C

US

INT-CL (IPC) : C25 D 3/38

Full	Title	Citation	Front	Review	Classification	Date	Reference	Sequences	Attachments	KMC	Draw	Desc	Image
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Terms	Documents
L2 and (organic with (leveller or leveler or levelling or leveling))	2

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